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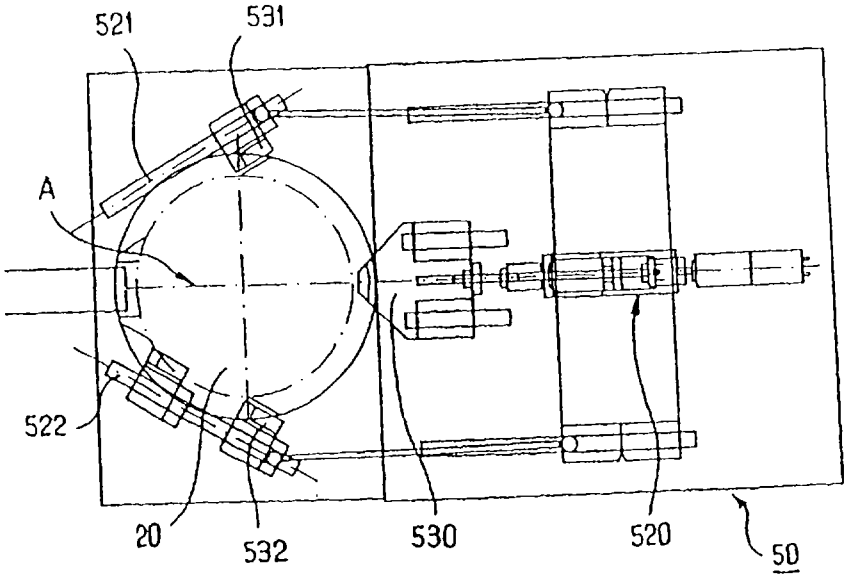
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(54) Title: SUBSTRATE - LAYER CUTTING DEVICE AND METHOD ASSOCIATED THEREWITH



(57) Abstract: The invention relates to a device (40) for automatic high-precision cutting of a layer of material joined to a source substrate by means of an embrittled area, said source substrate and layer forming an assembly which is to be cut and said device comprising cutting means (531, 532) in addition to means (510) for maintaining the position of the assembly which is to be cut, characterised in that the cutting means comprises a blade which acts upon the assembly which is to be cut. The invention also relates to a method for using said device.

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